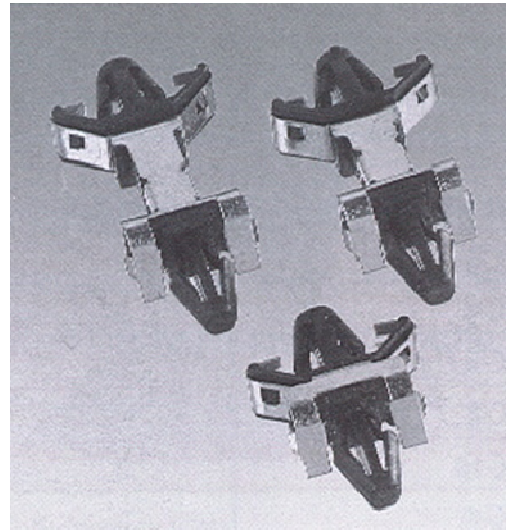


## FRAME GROUNDING SPACER

The grounding function is combined with resin-made spacer (patented)  
Resin made spacer combined with tin plated phosphor bronze is used for suppression of EMI and ESD on the PCB.

### Key Features

Pressure developed by plastic and metal fingers provide contact over P.C. card for excellent electrical current passage.  
Stable contact resistance is gained  
Contact resistance doesn't vary in the heat cycle test  
Even if the screw can not stand at the center of the PCB, the ground can be provided as desired  
Maintenance can be carried out easily  
The number of parts is reduced  
The cost is reduced considerably



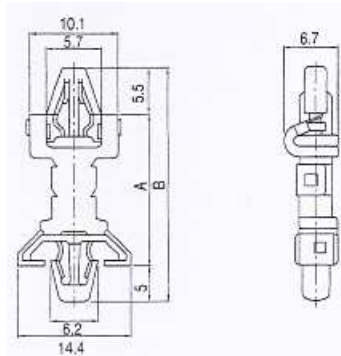
### Specifications

Material

Resin part: polyphenylene ether

Metal part: Tin plated phosphor bronze

UL standard (resin part): UL94V-0



Part number	Unit: mm	
	A	B
CEMMENT00001	14.4	24.9
CEMMENT00005	11.4	21.9
CEMMENT00007	17.7	28.2
CEMMENT00008	20.0	30.5
CEMMENT00009	9.8	20.3

## FRAME GROUNDING EDGE SPACER

A grounding function is added to the supporting structure as well as open/close functions of the printed circuit board. Frame grounding can be taken from the P.C.board spacer in the equipment which requires opening/closing of the P.C.board during maintenance.

### Key Features

Fire-resistant material is used (equivalent to UL94V-0)

### Specifications

Ref: CEMENT00010

Material:

Resin part :PPHOX

Metal part: tin plated phosphor bronze

Applicable board thickness:

PC board 1.6mm

Chassis side t 0.8mm—t 2.3mm

